



## Material Content Data Sheet



<b>Sales Product Name</b>		BFR 843EL3 E6327		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001642152						
<b>Package</b>		PG-TSLP-3-10		<b>Weight*</b>		0.47 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.01		84	
	noble metal	gold	7440-57-5	0.004	0.84		8382	
	inorganic material	silicon	7440-21-3	0.024	5.16	6.01	51641	60107
leadframe	non noble metal	nickel	7440-02-0	0.073	15.63	15.63	156326	156326
wire	noble metal	gold	7440-57-5	0.009	1.94	1.94	19351	19351
encapsulation	organic material	carbon black	1333-86-4	0.002	0.36		3560	
	plastics	epoxy resin	-	0.048	10.32		103250	
	inorganic material	silicondioxide	60676-86-0	0.281	60.52	71.20	605262	712072
leadfinish	noble metal	gold	7440-57-5	0.010	2.26	2.26	22563	22563
plating	noble metal	palladium	7440-05-3	0.003	0.70		7018	
	noble metal	gold	7440-57-5	0.010	2.26	2.96	22563	29581
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com